

IN THE CLAIMS:

The following is a complete listing of claims and replaces all prior versions and listings of claims in the present application:

1. - 25. (Cancelled)

26. (Currently Amended) A light-emitting diode arrangement, comprising:

~~a at least one~~ light-emitting diode chip;

a multi-layer board having a base of a thermally well-conducting material, the material including a in particular of metal, the base being a core of the board and configured for heat dissipation; and

an electrically insulating and thermally conducting connection layer between an emission surface of the light-emitting diode chip and the board, wherein between the light-emitting diode chip and the base of the board there is arranged an intermediate carrier separate from [[those]] parts with which the light-emitting diode chip is electrically contacted, and wherein the intermediate carrier includes ~~is formed by~~ an aluminum nitride substrate.

27. (Currently Amended) The light-emitting diode arrangement according to claim 26, wherein the electrically insulating connection layer is at least a boundary surface of the light-emitting diode chip, which is arranged towards the board.

28. (Previously Presented) The light-emitting diode arrangement according to claim 26, wherein the electrically insulating connection layer is at least an adhesive layer.

29. (Previously Presented) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is accommodated in a depression of the board.

30. (Previously Presented) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is arranged in a region of a depression in the base material of the board.

31. (Previously Presented) The light-emitting diode arrangement according to claim 29, wherein the light-emitting diode chip does not project beyond a contour of the board.

32. (Previously Presented) The light-emitting diode arrangement according to claim 29, wherein the light-emitting diode chip ends flush with an upper side of the board.

33. (Currently Amended) The light-emitting diode arrangement according to claim 29, wherein the depression functions as ~~has the function of~~ a reflector.

34. (Currently Amended) The light-emitting diode arrangement according to claim 29, wherein ~~the walls of~~ the depression includes walls that are at least partially beveled.

35. (Currently Amended) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is arranged so that the substrate of the light-emitting diode is towards the ~~[[plate]]~~ board.

36. (Currently Amended) The light-emitting diode arrangement according to claim 35, wherein ~~a~~ ~~[[the]]~~ substrate of the light-emitting diode chip is of an electrically insulating material.

37. (Currently Amended) The light-emitting diode arrangement according to claim 36, wherein the substrate of the light-emitting diode chip is formed of sapphire.

38. (Currently Amended) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is arranged so that ~~[[the]]~~ ~~a~~ substrate of the light-emitting diode chip ~~diodes~~ is away from the board.

39. (Currently Amended) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is arranged on the intermediate carrier using by means of a conductive adhesive.

40. (Previously Presented) The light-emitting diode arrangement according to claim 26, wherein a side of the intermediate carrier towards the board is electrically insulating.

41. (Previously Presented) The light-emitting diode arrangement according to claim 40, wherein a region of the intermediate carrier towards the light-emitting diode chip has conductive regions.

42. (Currently Amended) The light-emitting diode arrangement according to claim 26, wherein at least a region of the light-emitting diode chip is covered by ~~a lens in particular~~ a Fresnel lens.

43. (Previously Presented) The light-emitting diode arrangement according to claim 42, wherein a region between the board and the lens is at least partially filled by a colour conversion material.

44. (Previously Presented) The light-emitting diode arrangement according to claim 43, wherein the colour conversion material is arranged above and alongside the light-emitting diode chip.

45. (Currently Amended) The light-emitting diode arrangement according to claim 26, wherein the light emitting diode chip is connected to a circuit board using by means of wires, and the circuit board is applied to the board using by means of an insulating layer tying positioned therebetween.

46. (Currently Amended) A light-emitting ~~Light-emitting~~ diode arrangement, comprising:

a ~~at least one~~ light-emitting diode chip,

a multi-layer board[[.]] having a base of a thermally well-conducting layer, the layer including a in particular of metal, the base being a core of the board and configured for heat dissipation; and

an electrically insulating and thermally conducting connection layer between an emission surface of the light-emitting diode chip and the board, wherein between the light-emitting chip and the base of the board there is arranged an intermediate carrier separate from [[those]] parts with which the light-emitting diode chip is electrically contacted, and wherein a colour conversion material is arranged above and alongside the light-emitting diode chip.

47. (Currently Amended) A ~~light-emitting~~ light-emitting diode arrangement, comprising:

- ~~a at least one~~ light-emitting diode chip;
- a multi-layer board[[,] having a base of a thermally well-conducting layer, the layer including a in particular of metal, the base being a core of the board and configured for heat dissipation; and
- an electrically insulating and thermally conducting connection layer between an emission surface of the light-emitting diode chip and the board, wherein between the light-emitting chip and the base of the board there is arranged an intermediate carrier separate from [[those]] parts with which the light-emitting diode chip is electrically contacted, and wherein the light-emitting diode chip is arranged on the intermediate carrier using by means of a conductive adhesive.